

Data sheet acquired from Harris Semiconductor SCHS031B – Revised July 2003

# **CD4026B, CD4033B Types**

# CMOS Decade Counters/Dividers

High-Voltage Types (20-Volt Rating)
With Decoded 7-Segment Display Outputs and:
Display Enable — CD4026B
Ripple Blanking — CD4033B

■ CD4026B and CD4033B each consist of a 5-stage Johnson decade counter and an output decoder which converts the Johnson code to a 7-segment decoded output for driving one stage in a numerical display.

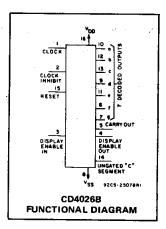
These devices are particularly advantageous in display applications where low power dissipation and/or low package count are important.

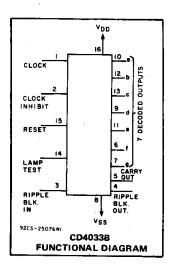
Inputs common to both types are CLOCK, RESET, & CLOCK INHIBIT; common outputs are CARRY OUT and the seven decoded outputs (a, b, c, d, e, f, g). Additional inputs and outputs for the CD4026B include DISPLAY ENABLE input and DISPLAY ENABLE and UNGATED "C-SEGMENT" outputs. Signals péculiar to the CD4033B are RIPPLE-BLANKING INPUT AND LAMP TEST INPUT and a RIPPLE-BLANKING OUTPUT.

A high RESET signal clears the decade counter to its zero count. The counter is advanced one count at the positive clock signal transition if the CLOCK INHIBIT signal is low. Counter advancement via the clock line is inhibited when the CLOCK INHIBIT signal is high. The CLOCK INHI-BIT signal can be used as a negative-edge clock if the clock line is held high. Antilock gating is provided on the JOHNSON counter. thus assuring proper counting sequence. The CARRY-OUT (Cout) signal completes one cycle every ten CLOCK INPUT cycles and is used to clock the succeeding decade directly in a multi-decade counting chain. The seven decoded outputs (a, b, c, d, e, f, g) illuminate the proper segments in a seven

#### Features:

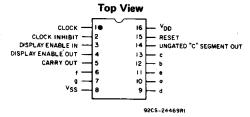
- Counter and 7-segment decoding in one package
- Easily interfaced with 7-segment display types
- Fully static counter operation: DC to 6 MHz (typ.) at V<sub>DD</sub>=10 V
- Ideal for low-power displays
- Display enable output (CD4026B)
- "Ripple blanking" and lamp test (CD4033B)
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Schmitt-triggered clock inputs
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices" Applications
- Decade counting 7-segment decimal display
- Frequency division 7-segment decimal displays
- Clocks, watches, timers
   (e.g. ÷60, ÷ 60, ÷ 12 counter/display)
- Counter/display driver for meter applications



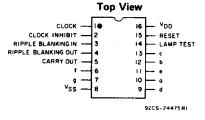


segment display device used for representing the decimal numbers 0 to 9. The 7-segment outputs go high on selection in the CD4033B; in the CD4026B these outputs go high only when the DISPLAY ENABLE IN is high.

#### TERMINAL DIAGRAMS



#### CD4026B



CD4033B

# MAXIMUM RATINGS, Absolute-Maximum Values: DC SUPPLY-VOLTAGE RANGE, (VDD) -0.5V to +20V Voltages referenced to VSS Terminal) -0.5V to +20V INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to VDD +0.5V DC INPUT CURRENT, ANY ONE INPUT ±10mA POWER DISSIPATION PER PACKAGE (PD): 500mW For TA = -55°C to +100°C 500mW For TA = +100°C to +125°C Derate Linearity at 12mW/°C to 200mW DEVICE DISSIPATION PER OUTPUT TRANSISTOR 100mW FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW OPERATING-TEMPERATURE RANGE (Ta) -55°C to +125°C STORAGE TEMPERATURE RANGE (Tstg) -65°C to +150°C LEAD TEMPERATURE (DURING SOLDERING): At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max +265°C

#### **RECOMMENDED OPERATING CONDITIONS**

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	VDD		UNITS		
A CONTRACTOR OF THE CONTRACTOR	(V)	MIN.	MAX.	00	
Supply-Voltage Range (For T <sub>A</sub> Temperature Range)	\ = Full Package		3	18	V
Clock Input Frequency, 1	CL	5 10 15	- -	2.5 5.5 8	MHz
Clock Pulse Width,	WCL.	5 10 15	220 100 80	- - -	
Clock Rise and Fall Time, 1	rCL <sup>, t</sup> fCL	5 10 15	- 	Unlimited	:
Clock Inhibit Set Up Time, t	SU	5 10 15	200 50 30	- -	ns
Reset Pulse Width, t	W	5 10 15	200 100 50	- - -	e.
Reset Removal Time		5 10 15	30 15 10	- -	

#### STATIC ELECTRICAL CHARACTERISTICS

CHARACTER-	CONE	OITIO	ıs	LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
ISTIC	Vo	VIN	$v_{DD}$						+25		
	(V)	(V)	(V)	-55	<del>-4</del> 0	+85	+125	Min.	Тур.	Max.	
Quiescent Device	-	0,5	5	5	5	150	150		0.04	5	
Current,		0,10	10	10	10	300	300	_	0.04	10	μА
IDD Max.	-	0,15	15	20	20	600	600	-	0.04	20	]
	_	0,20	20	100	100	3000	3000	-	0.08	100	
Output Low	0.4	0,5	- 5	0.64	0.61	0.42	0.36	0.51	1	-	
(Sink) Current	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	. 1	
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	]
Output High (Source) Current, IOH Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1		mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	1	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	:	
	13.5	0,15	15	-4.2	-4	2.8	-2.4	-3.4	-6.8	-	
Output Voltage:	_	0,5	5	0.05				-	0	0.05	
Low-Level,	_	0,10	10		0	.05		+	- 0	0.05	
VOL Max.	_	0,15	15	0.05					0	0.05	v
Output Voltage:	_	0,5	5	4.95			4.95	5	-	v	
High Level,	-	0,10	10		9.95				10		-
VOH Min.	_	0,15	15		14	.95		14.95	15	-	
Input Low	0.5, 4.5	_	5		1	.5		-		1.5	
Voltage,	1, 9	_	10			3			_	3	
VIL Max.	1.5,13.5	_	15			4		-	<u> </u>	4	l v
Input High Voltage, VIH Min.	0.5, 4.5	-	5		;	3.5		3.5	_		\ \ \
	1, 9		10		7			7	_	-	
	1.5,13.5	-	15			1		11	<u> </u>	_	]
Input Current IN Max.	-	0,18	18	±0.1	±0.1	±1	±1		±10 <sup>-5</sup>	±0.1	μΑ

#### CD4026B

When the DISPLAY ENABLE IN is low the seven decoded outputs are forced low regardless of the state of the counter. Activation of the display only when required results in significant power savings. This system also facilitates implementation of display-character multiplexing.

The CARRY OUT and UNGATED "C-SEGMENT" signals are not gated by the DISPLAY ENABLE and therefore are available continuously. This feature is a requirement in implementation of certain divider functions such as divide-by-60 and divide-by-12.

#### CD4033B

The CD4033B has provisions for automatic blanking of the non-significant zeros in a multi-digit decimal number which results in an easily readable display consistent with normal writing practice. For example, the number 0050.0700 in an eight digit display would be displayed as 50.07. Zero suppression on the integer side is obtained by connecting the RBI terminal of the CD4033B associated with the most significant digit in the display to a low-level voltage and connecting the RBO terminal of that stage to the RBI terminal of the CD4033B in the next-lower significant position in the display. This procedure is continued for each succeeding CD4033B on the integer side of the display.

On the fraction side of the display the RBI of the CD4033B associated with the least significant bit is connected to a low-level voltage and the RBO of that CD4033B is connected to the RBI terminal of the CD4033B in the next more-significant-bit position. Again, this procedure is continued for all CD4033B's on the fraction side of the display.

In a purely fractional number the zero immediately preceding the decimal point can be displayed by connecting the RBI of that stage to a high level voltage (instead of to the RBO of the next more significant-stage). For example: optional zero → 0.7346. Likewise, the zero in a number such as 763.0 can be displayed by connecting the RBI of the CD4033B associated with it to a high-level voltage.

Ripple blanking of non-significant zeros provides an appreciable savings in display power.

The CD4033B has a LAMP TEST input which, when connected to a high-level voltage, overrides normal decoder operation and enables a check to be made on possible display malfunctions by putting the seven outputs in the high state.

The CD4026B- and CD4033B-series types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

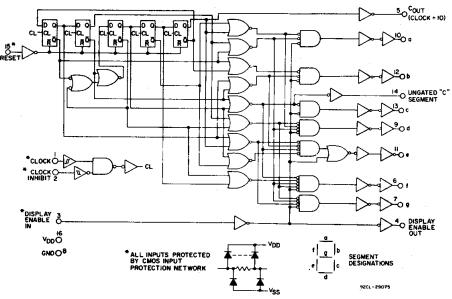


Fig. 1 - CD4026B logic diagram.

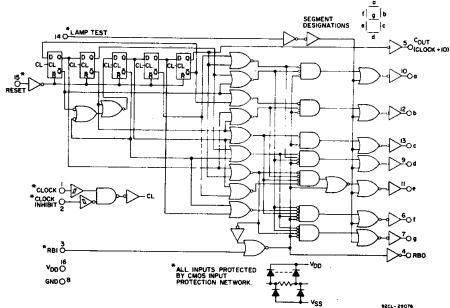


Fig. 2 - CD4033B logic diagram.

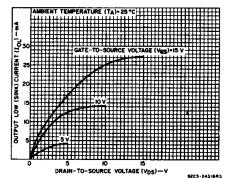


Fig. 6 — Typical n-channel output low (sink) current characteristics.

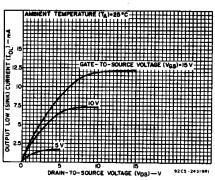


Fig. 7 — Minimum n-channel output low (sink) current characteristics.

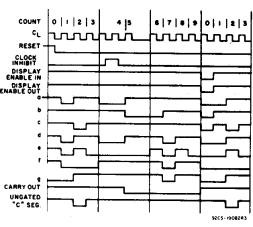


Fig. 3 — CD4026B timing diagram.

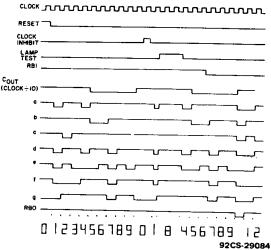


Fig. 4 -- CD4033B timing diagram.

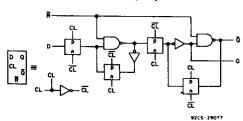


Fig. 5 - Detail of typical flip-flop stage for both types.

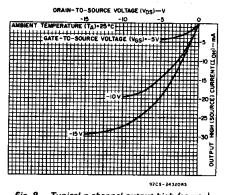


Fig. 8 — Typical p-channel output high (source) current characteristics.

# DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A$ = 25°C, Input $t_r$ , $t_f$ = 20 ns, $C_L$ = 50 pF, $R_L$ = 200 k $\Omega$

		TEST CONDITIONS			LIMIT	s	
CHARACTERISTIC			V <sub>DD</sub>	t -		Max.	UNITS
CLOCKED OPERATION					• •		·
Propagation Delay Time;	<sup>t</sup> PLH <sup>, t</sup> PHL		5	_	250	500	
Carry-Out Line		•	10 15		100	200	
<u> </u>		<del> </del>	<del> </del>		75	150	
Decode Outlines			5	_	350	700	
			10		125	250	ns
Transition Time:			15		90	180	
Carry-Out Line	<sup>t</sup> THL <sup>, t</sup> TLH		5	<u> </u>	100	200	
Carry-Out Line	÷ .		10	-	50	100	
Marrian Charles 5		<del>                                      </del>	15	-	25	50	
Maximum Clock Input Fred	dneuch, tCT▼		5	2.5	5	<u> </u>	
Secretaria de la compansión de la compan			10	5.5	11	-	MHz
			15	8	16	<u> </u>	
Min. Clock Pulse Width,	t <sub>W</sub> .	÷	5		110	220	
			10		50	100	
Clock and Clock Inhibit Di			15		40	80	
Clock and Clock Inhibit Ris			5				
	<sup>t</sup> rCL <sup>, t</sup> fCL	4,	10 15	Un	limite	d	ns
Average Input Capacitance,	CIN	Any Input		_	5	7	рF
RESET OPERATION							
Propagation Delay Time;			5	_	275	550	
To Carry-Out Line,	<sup>t</sup> PLH		10	_	120	240	
		1	15	_	80	160	
To Decode Out Lines,	<sup>t</sup> PHL <sup>, t</sup> PLH		5	_	300	600	
			10	_	125	250	
			15	-	90	180	ns
Min. Reset Pulse Width,	ťw		5	_	100	120	
j.			10	-	50	100	
		1	15	_	25	50	
Ain. Reset Removal Time			5	_	0	30	
			10	-	0	15	
<u> </u>			15	_ ]	0	10	

<sup>▲</sup> Measured with respect to carry-out line.

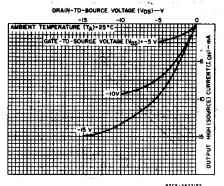


Fig. 9 – Minimum p-channel output high (source) current characteristics.

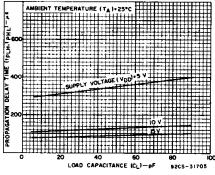


Fig. 10 — Typical propagation delay time as a function of load capacitance for decoded outputs.

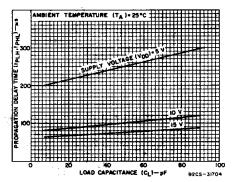


Fig. 11 — Typical propagation delay time as a function of load capacitance for carry-out outputs.

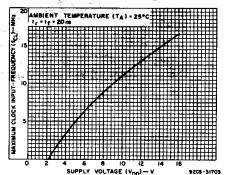
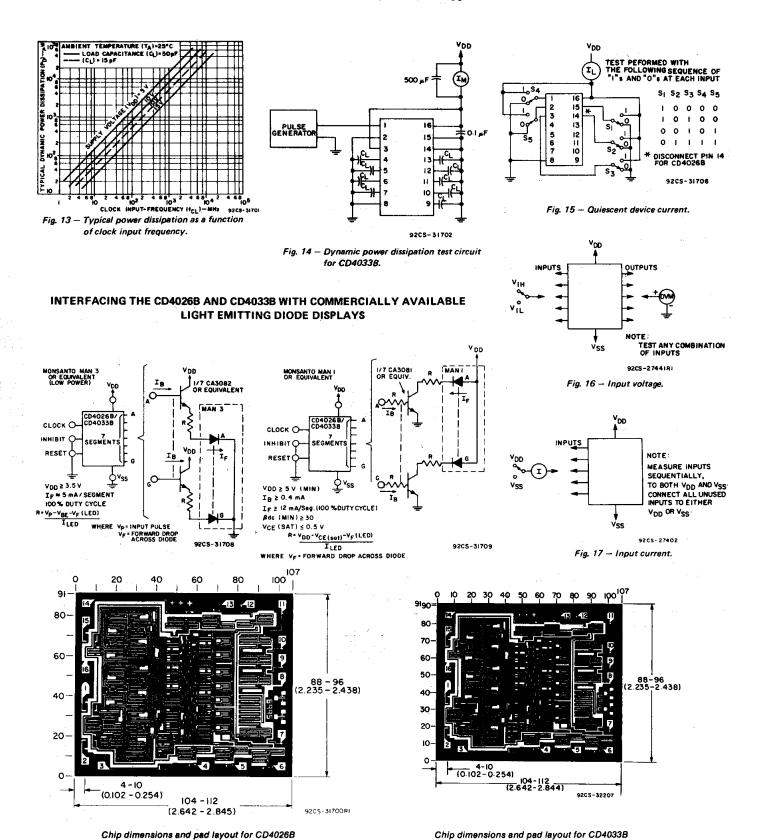


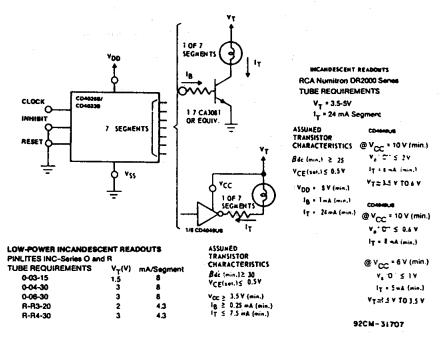
Fig. 12 - Typical maximum clock input-frequency as a function of supply voltage.



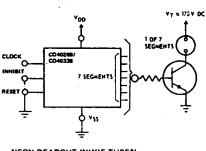
Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10<sup>-3</sup> inch).

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# INTERFACING THE CD4026B AND CD4033B WITH COMMERCIALLY AVAILABLE 7-SEGMENT DISPLAY DEVICES\*



\* The interfacing buffers shown, while a necessity with the CD4026A and CD4033A, are not required when using the "B" devices; the "B" outputs (≈ 10 times the "A" outputs) can drive most display devices directly especially at voltages above 10 V.



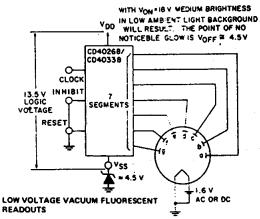
NEON READOUT (NIXIE TUBE\*)

- 1. Alco Electronics -- MG19
- 2. Burroughs 85971, B7971, B8971

TUBE REQUIREMENTS	mA Segme		
Alco MG19	180	. 0.5	
Burroughs B5971	170	. 3	
Burroughs B7971, B8971.	170	. 6	

▲ (Trademark) Burroughs Corp.
TRANSISTOR CHARACTERISTICS
Leakage with transistor cutoff — 0.05 mA

 $V(BR)CER \cdot \cdot \cdot \cdot > V_{\Upsilon}$  $\beta_{dc}$  (min.)  $\geq 30$  92CS-31710



- 1. Tung-Sol DIGIVAC S/G ‡ Type DT1704A or DT1705C
- 2. Nippon Electric (NEC); Type DG12E or LD915 TUBE REQUIREMENTS: 100 to 300 µA/segment at tube voltages of 12 V to 25 V depending on required brightness Filament requirement 45 m ≠ at 1.6 V, ac or dc.
- 3 (Trademark) Wagner Electric Co.

92 (5-317)

# PACKAGE OPTION ADDENDUM

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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD4026BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4026BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4026BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4026BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4033BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4033BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4033BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4033BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4033BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



# PACKAGE OPTION ADDENDUM

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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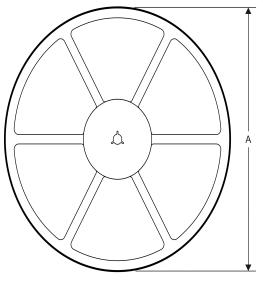
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

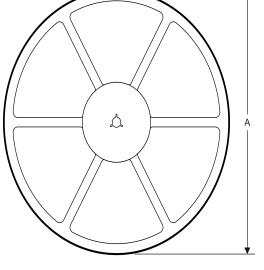
# PACKAGE MATERIALS INFORMATION

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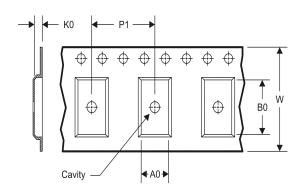
# TAPE AND REEL INFORMATION

## **REEL DIMENSIONS**





## **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## TAPE AND REEL INFORMATION

# \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4026BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4026BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4026BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4026BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



PW (R-PDSO-G16)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



# PW (R-PDSO-G16)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

# PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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